

SOT1086-3

plastic, thermal enhanced very thin small outline package; no leads; 14 terminals

10 June 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HVSON14
Package type industry code	HVSON14
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	MO-229
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	30-8-2011

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		4.4	-	4.5	4.6	mm
E	package width		2.9	-	3	3.1	mm
A	seated height		0.8	-	0.85	1	mm
A ₂	package height		-	-	-	-	
e	nominal pitch		-	-	0.65	-	mm
n ₂	actual quantity of termination		-	-	14	-	



2. Package outline

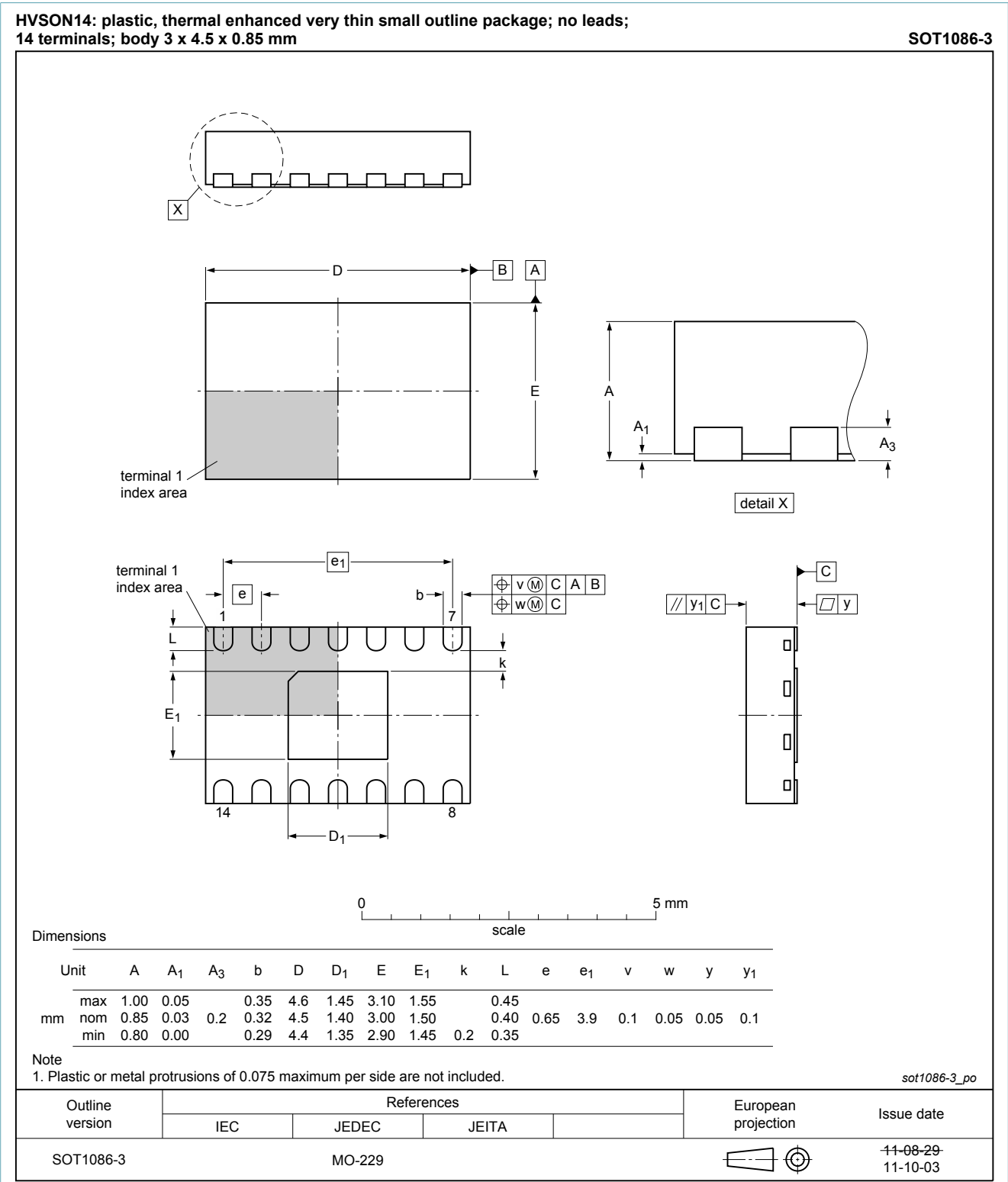


Fig. 1. Package outline HVSON14 (SOT1086-3)

3. Soldering

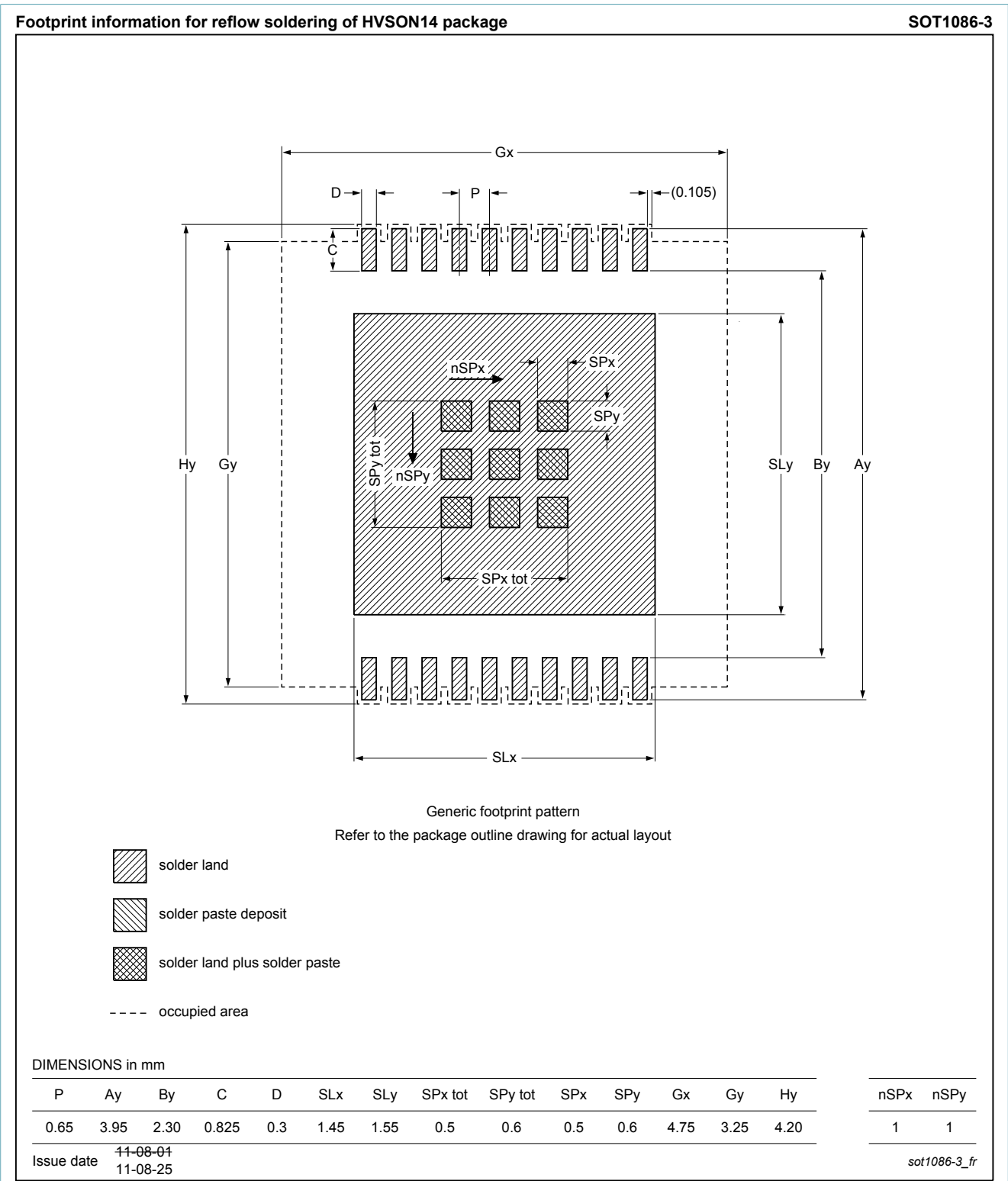


Fig. 2. Reflow soldering footprint for HVSON14 (SOT1086-3)

4. Legal information

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